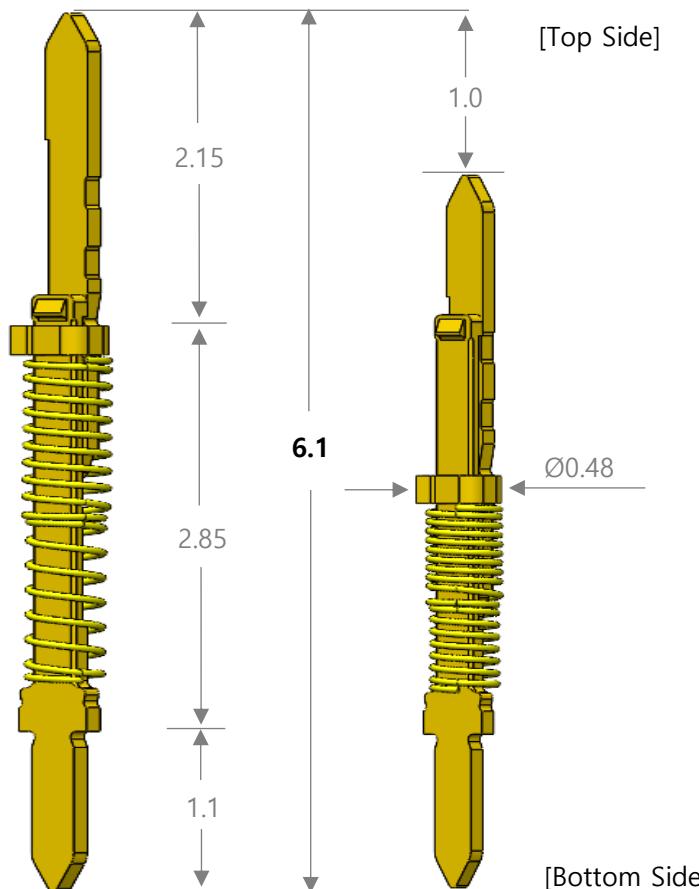


3. Products – 1) Stamped Probe Pin

Application

- LGA , Interposer
- 0.8P , 1.0P , 1.27P



Mechanical Spec.

Recommended Travel	10.0 gf±12% @ 1.00mm
Full Travel	14.5 gf±12% @ 1.30mm
Temperature	-40 °C ~ 150 °C

Material & Plating

Part	Material	Plating
Top/Bottom Plunger	Hardened BeCu	Ni, Au Plated
Spring	Stainless Steel	Ni, Au Plated

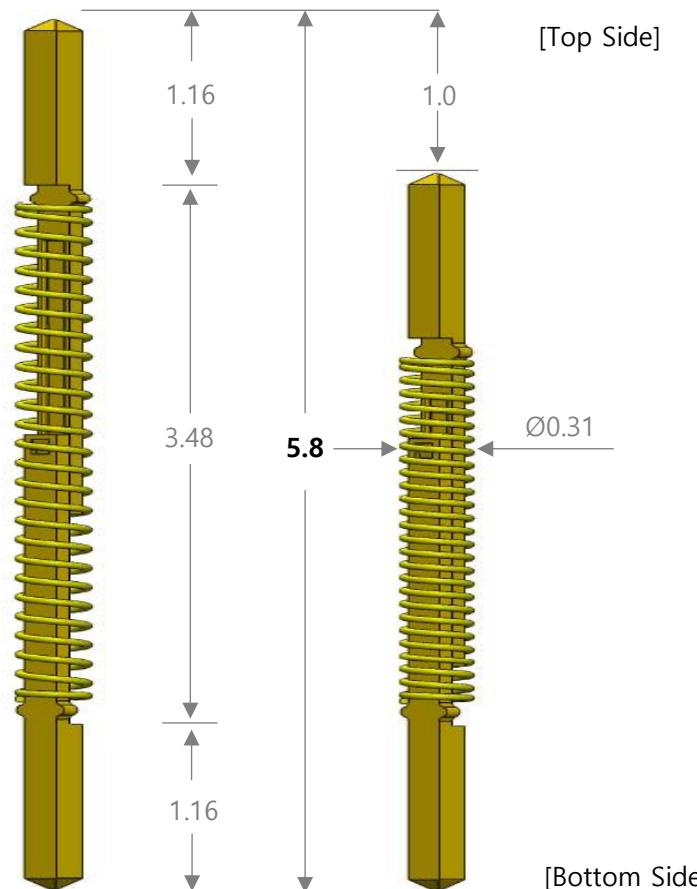
Electrical Spec.

Current Rating	3A Continuous
Resistance	> 100mΩ
Insertion Loss	12.35GHz @ -1dB
Return Loss	8.47GHz @ -20dB

3. Products – 1) Stamped Probe Pin

Application

- LGA , Interposer
- 0.5P Over



Mechanical Spec.

Recommended Travel	7.0 gf±10% @ 1.00mm
Full Travel	10.0 gf±10% @ 1.35mm
Temperature	-40 °C ~ 150 °C

Material & Plating

Part	Material	Plating
Top/Bottom Plunger	Hardened BeCu	Ni, Au Plated
Spring	Stainless Steel	Ni, Au Plated

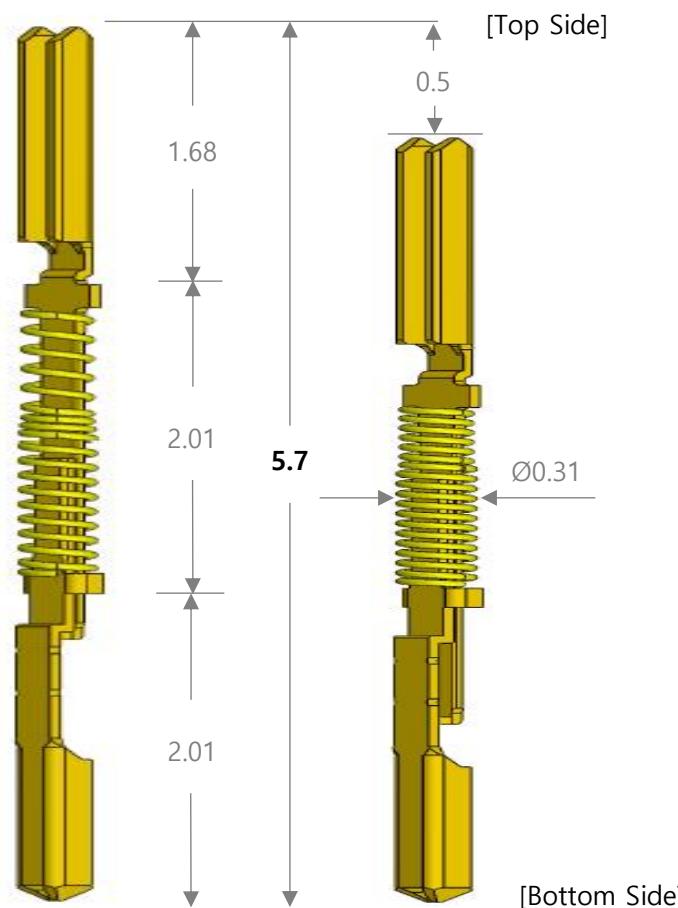
Electrical Spec.

Current Rating	3A Continuous
Resistance	≤150mΩ
Insertion Loss	10.04GHz @ -1dB
Return Loss	7.86GHz @ -20dB

3. Products – 1) Stamped Probe Pin

Application

- BGA , LGA , QFP , TSOP
- 0.4P Over



Mechanical Spec.

Recommended Travel	15.0 gf±10% @ 0.50mm
Full Travel	18.0 gf±10% @ 0.60mm
Temperature	-40 °C ~ 150 °C

Material & Plating

Part	Material	Plating
Top/Bottom Plunger	Hardened BeCu	Ni, Au Plated
Spring	Stainless Steel	Ni, Au Plated

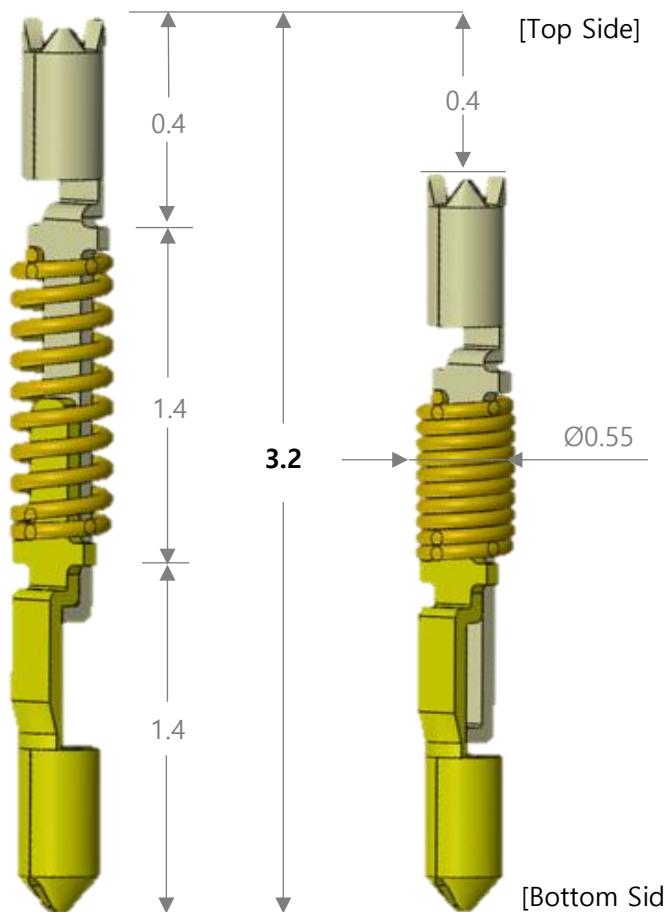
Electrical Spec.

Current Rating	3A Continuous
Resistance	≤100mΩ
Insertion Loss	9.70GHz @ -1dB
Return Loss	4.84GHz @ -20dB

3. Products – 1) Stamped Probe Pin

Application

- BGA , LGA , QFP , QFN , TSOP
- 0.8P , 1.0P , 1.27P



Mechanical Spec.

Recommended Travel	20.0 gf±10% @ 0.40mm
Full Travel	25.0 gf±10% @ 0.55mm
Temperature	-40 °C ~ 150 °C

Material & Plating

Part	Material	Plating
Top/Bottom Plunger	Hardened BeCu	Ni, Au Plated
Spring	Stainless Steel	Ni, Au Plated

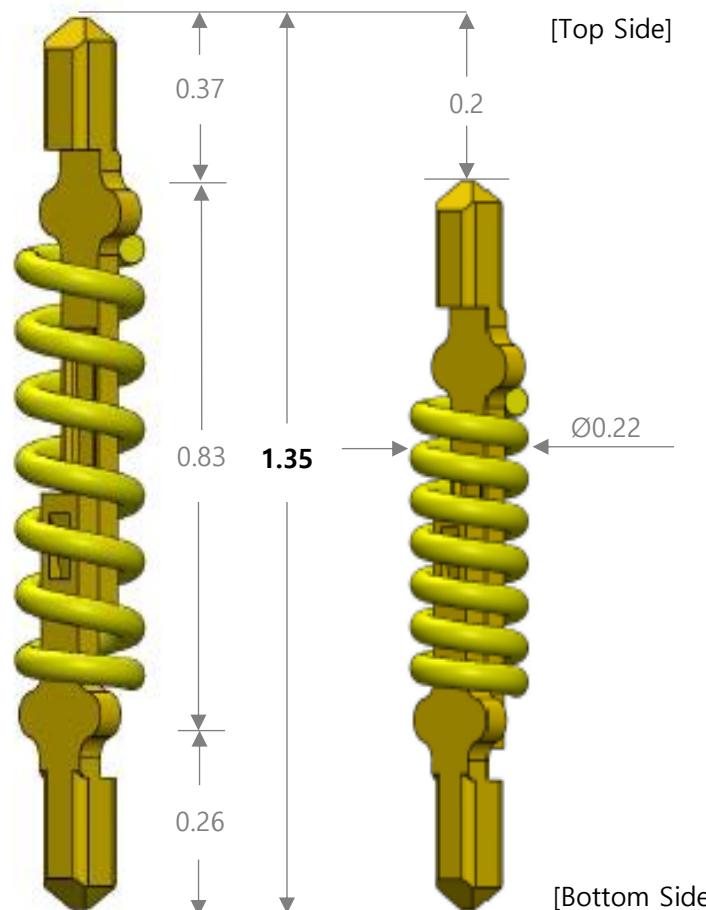
Electrical Spec.

Current Rating	3A Continuous
Resistance	≤100mΩ
Insertion Loss	31.37GHz @ -1dB
Return Loss	12.66GHz @ -20dB

3. Products – 1) Stamped Probe Pin

Application

- BGA , LGA , QFP , QFN , TSOP
- 0.3P



Mechanical Spec.

Recommended Travel	20.0 gf±10% @ 0.20mm
Full Travel	25.0 gf±10% @ 0.25mm
Temperature	-40 °C ~ 150 °C

Material & Plating

Part	Material	Plating
Top/Bottom Plunger	Hardened BeCu	Ni, Au Plated
Spring	Stainless Steel	Ni, Au Plated

Electrical Spec.

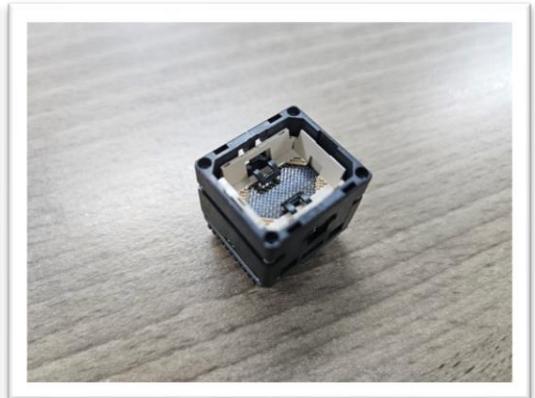
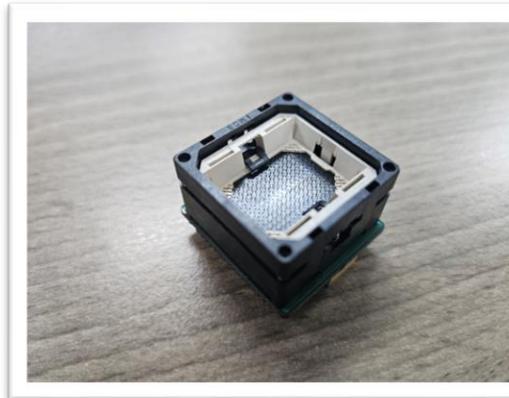
Current Rating	2A Continuous
Resistance	≤100mΩ
Insertion Loss	35.01GHz @ -1dB
Return Loss	19.16GHz @ -20dB

3. Products – 2) Test & Burn-in Socket



Clam Shell Type

Rotary Type



Heat Sink Type

Open Top Type

3. Products – 2) Test Socket

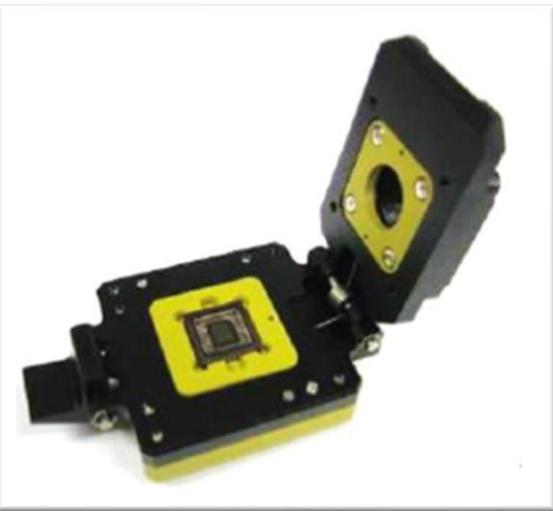
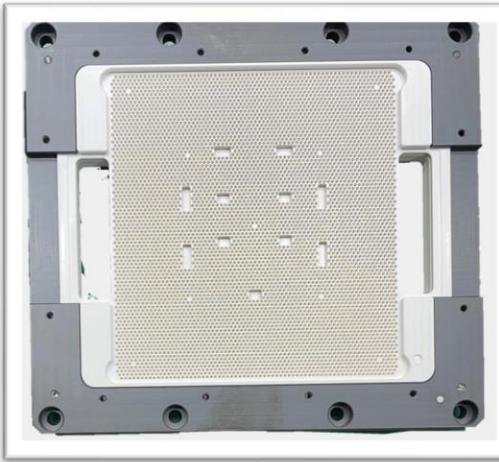
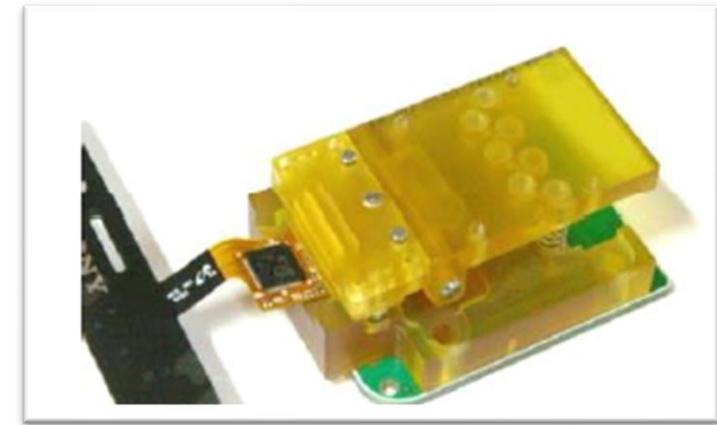


Image Sensor



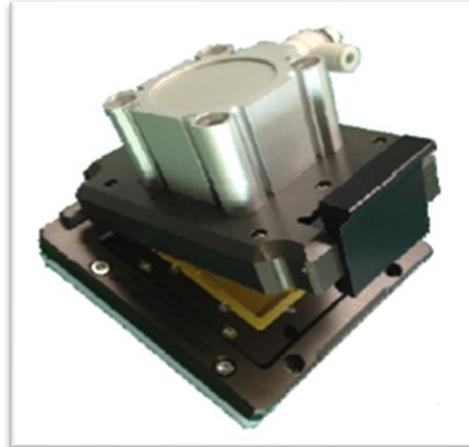
Pin Block



Clamp Type



FPCB Test JIG

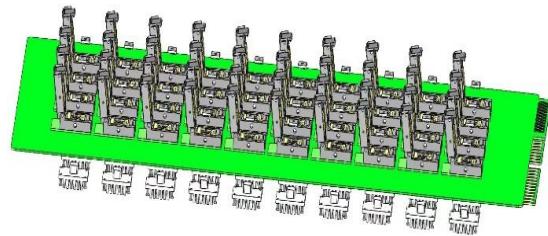
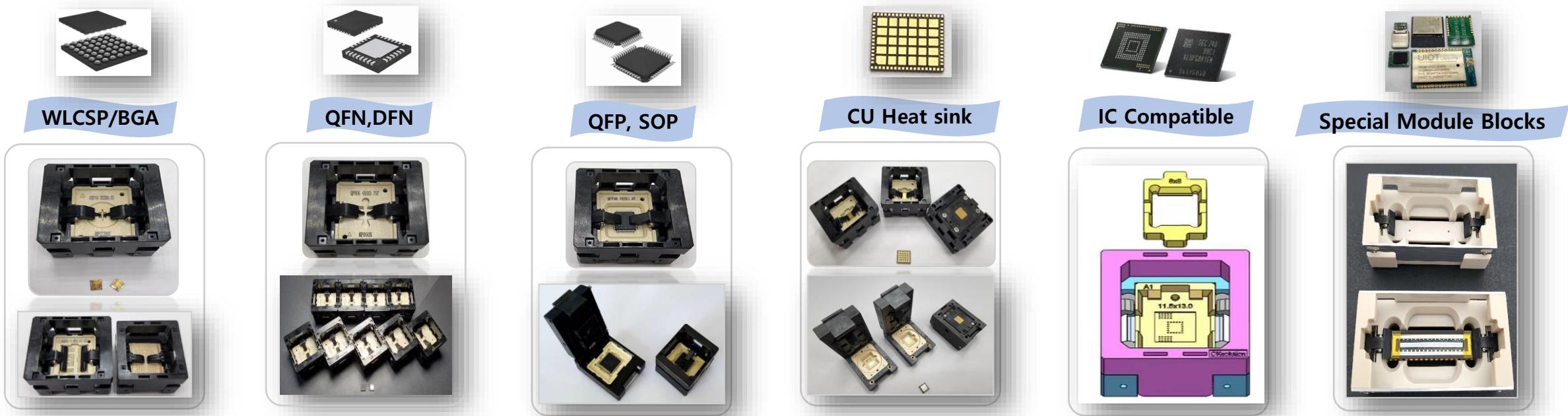


Air Cylinder Type

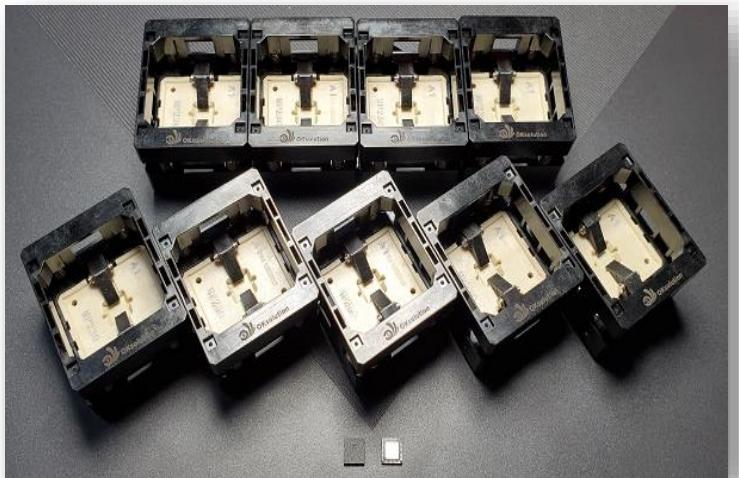


Dead Bug Socket

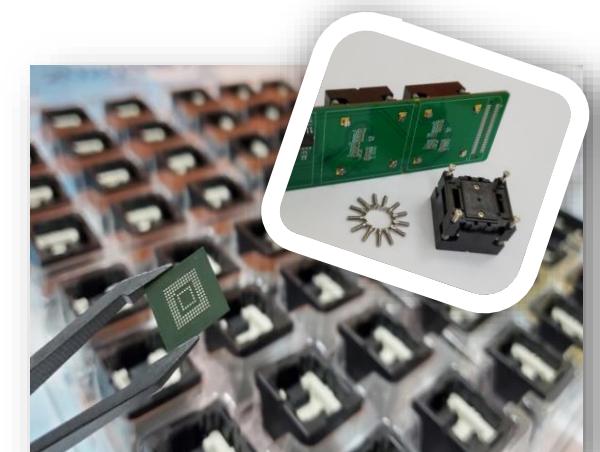
3. Products - 2) Test Socket



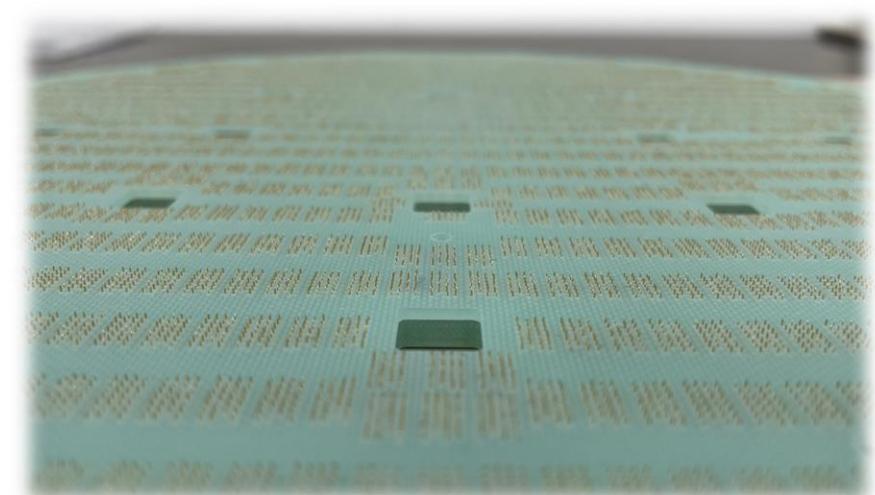
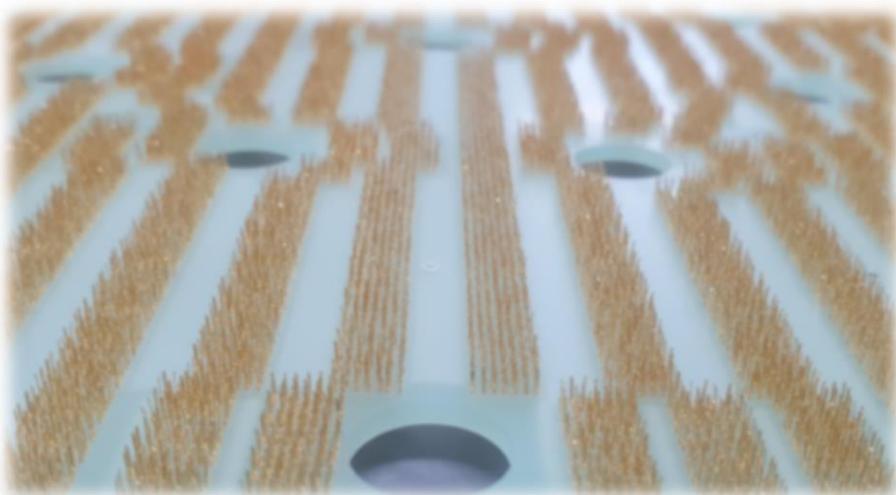
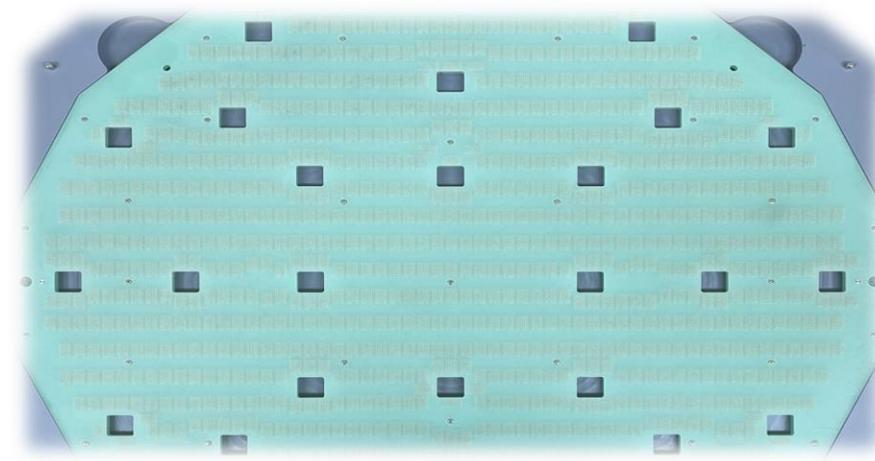
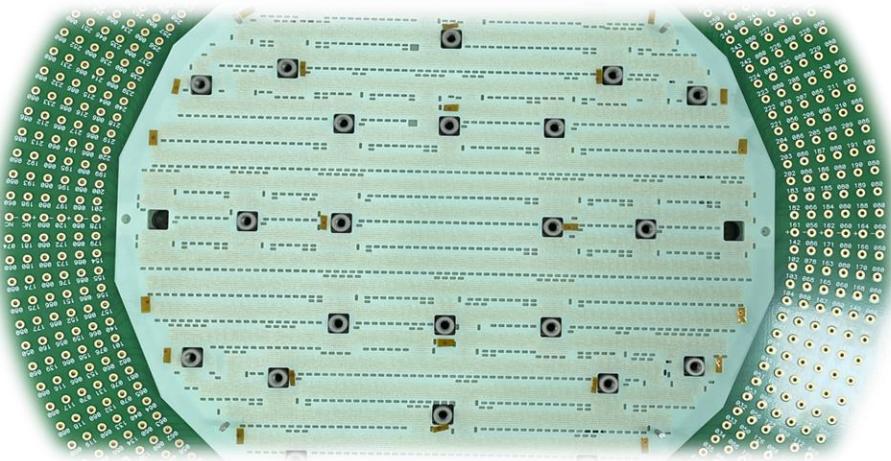
3. Products - 2) Test Socket



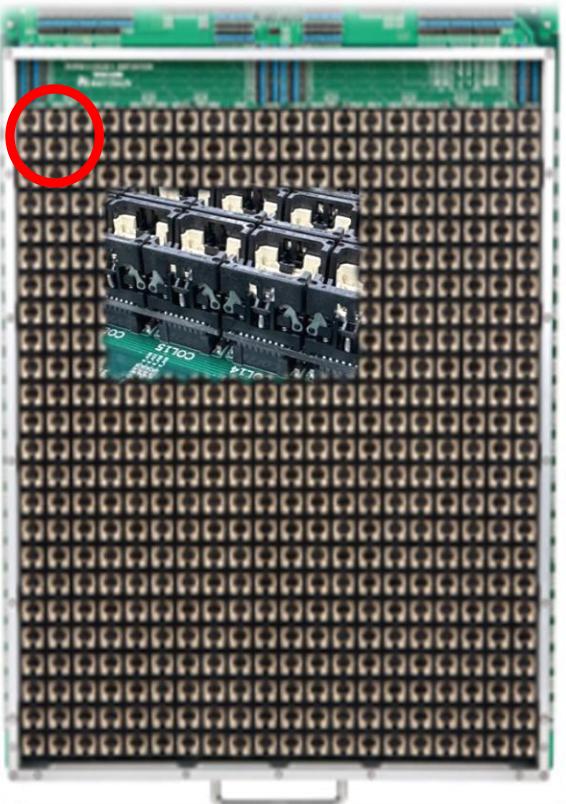
- ① Lead Time in 20 days
- ② Cost-efficient socket
- ③ Coverage anyone IC Package
- ④ Applied high performance Probe Pin in Socket
- ⑤ Socket size : 26x26, 28x32



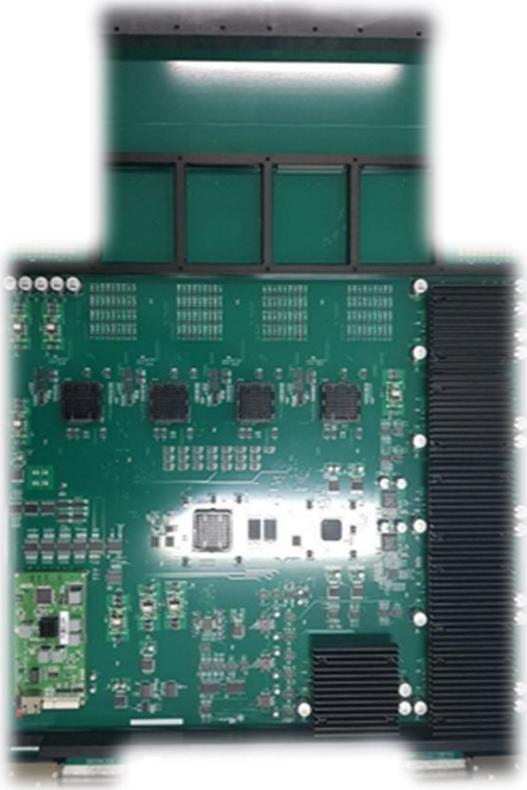
3. Products – 3) Interposer



3. Products – 4) Test & Burn-in Board



Burn-In Board



System Board

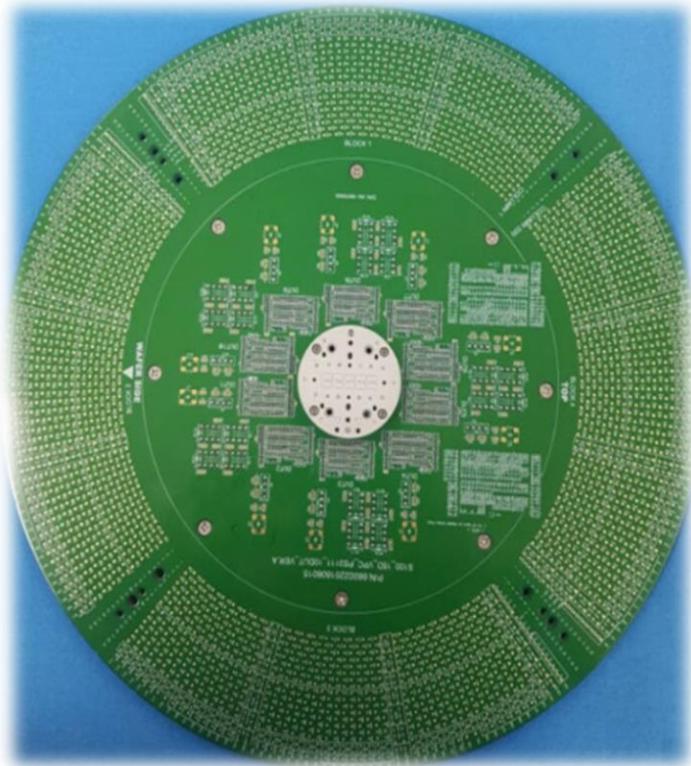


Logic BIB



HAST Board

3. Products – 5) SMT & Assembly



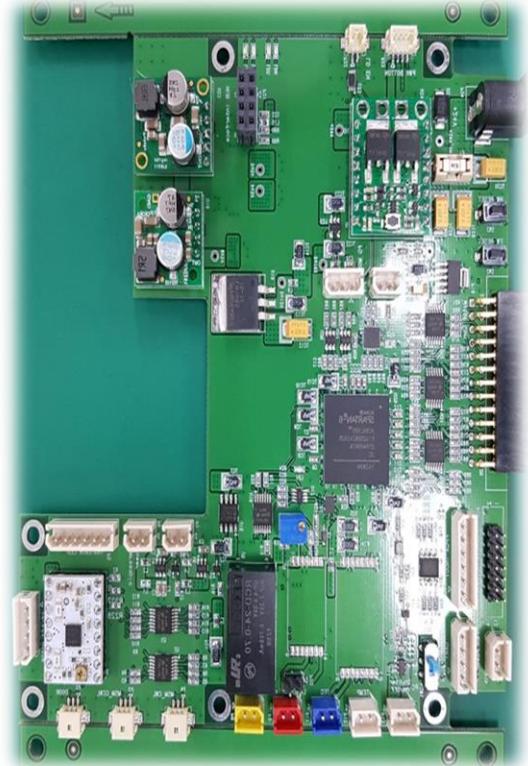
Probe Card



LCD System Board

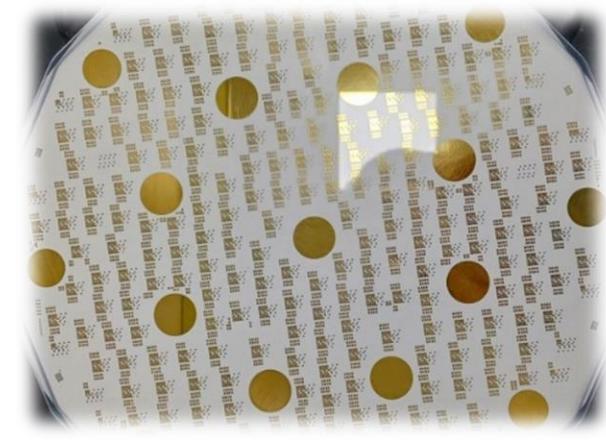
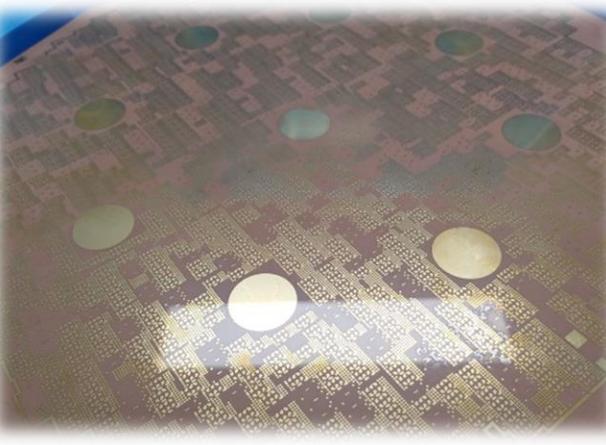
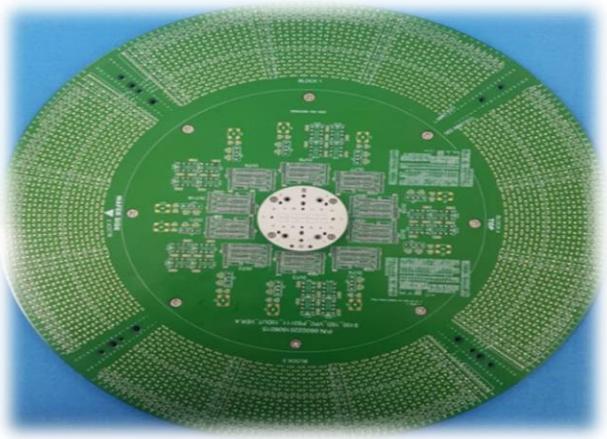
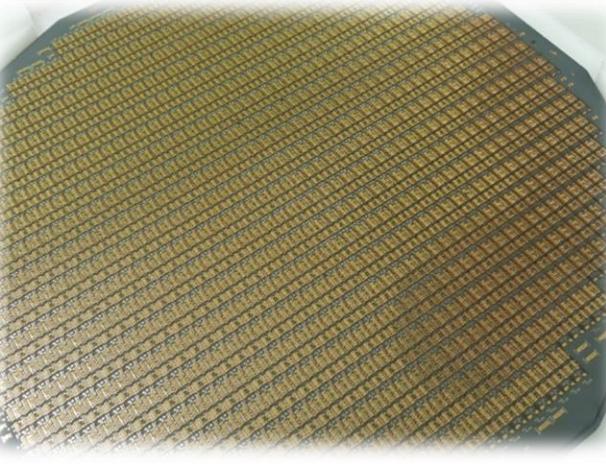
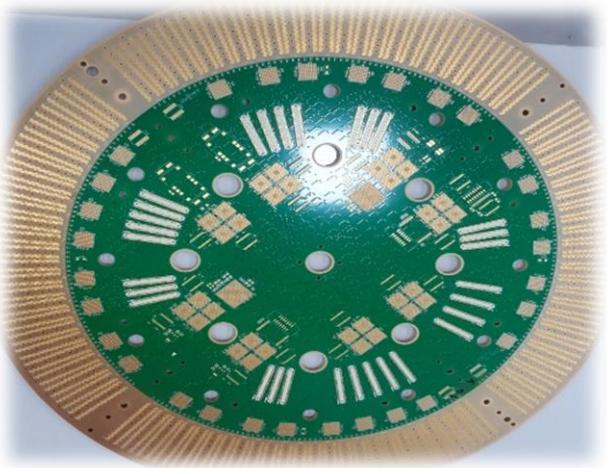


Fan Controller



Tester Board

3. Products - 5) SMT & Assembly



Probe Card

3. Products – 6) Fixture & Jig



Ass'y Jig



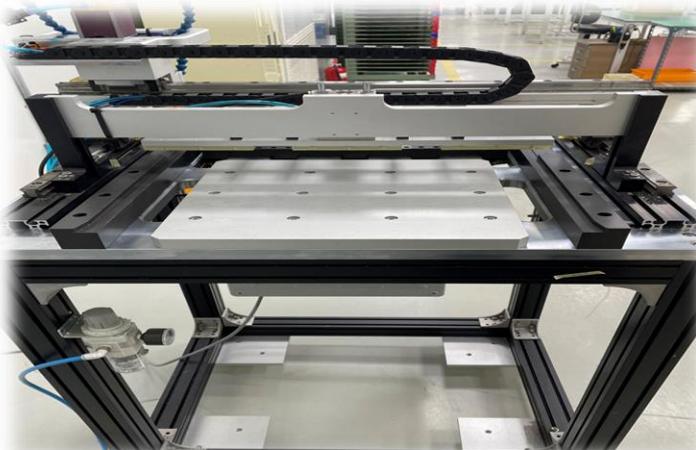
Test Jig



Test Board Frame



Test Board Frame



Cutting Jig



Rack Case

4. Equipment



Maker	FANUC' Robodrill Series (α -D21MiB5)
Dimension (X x Y x Z)	500 x 400 x 330 (mm)
RPM	10,000 ~ 24,000 (r/min)
Material	Torlon, Peek, Ceramic Peek, Ultem
Application	Precision Machining Hole
Q'ty	16
Product	Test Socket, Module Socket, RF Socket

5. Production Line



FANUC's Robodrill

5. Production Line

SMT Line



Rework Station



Retouch Line



Cleaning Room



TEST Line



5. Production Line

Wave Solder



Bonding Line



Selective Solder



Insert Line



Application Line



Assembly



6. Inspection Line

X-Ray Inspector



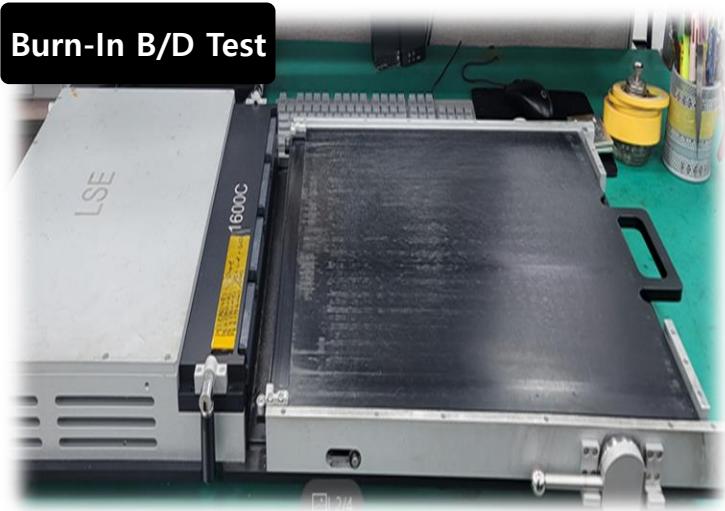
Vision Inspection



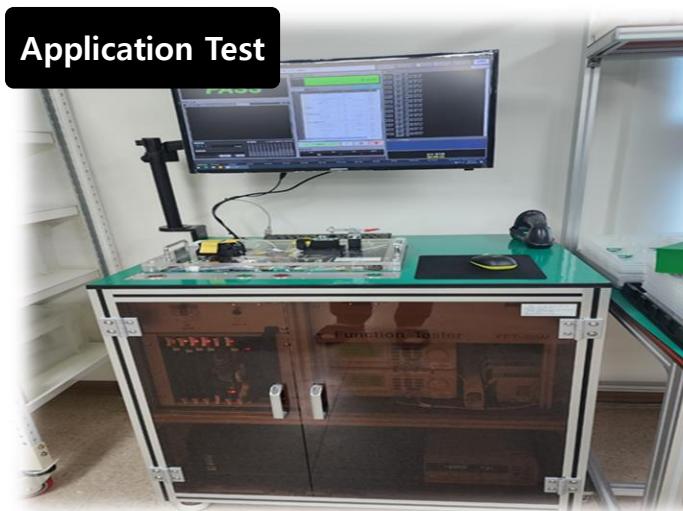
Auto BBT Test



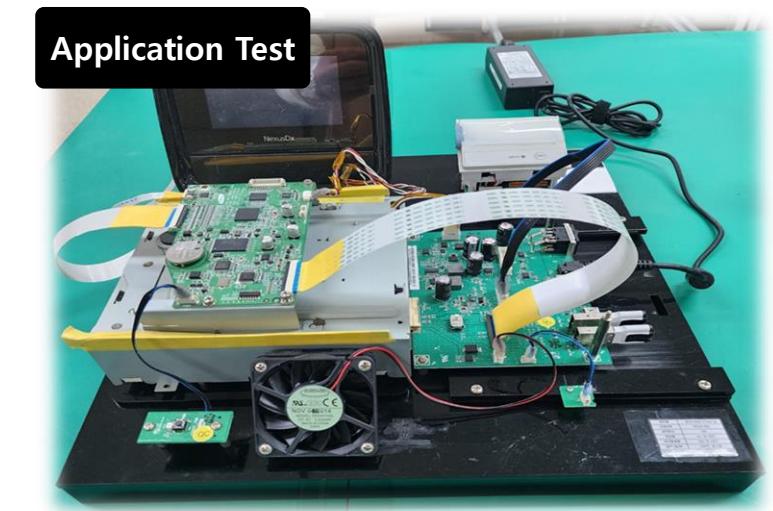
Burn-In B/D Test



Application Test



Application Test



6. Inspection Line

Visual Inspection Room



Vision Inspection



Automated Visual Inspection



Global 2D Inspection



Zeiss 2D Inspection



Microscope

